

PUBLICATIONS

Selected copies of publications can be found under the individual research topics.

BOOKS

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2. D. Doane and P. Franzon: *Multichip Modules: Basics and Alternatives*, 1993, by Van Nostrand Reinhold.
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BOOK CHAPTERS

1. P. Franzon, *Design for 3-D Integration*, 3-D IC Integration: Technology and Applications, P. Garrou, P. Ramm, C. Bower, (editors), Wiley VCH, May 2008.
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5. S. Mehrotra and P. Franzon, *Performance Driven Global Routing and Wiring Rule Generation for High Speed PCBs and MCMs*, in *Advanced Routing of Electronic Modules*, M. Pecht (editor), (Kluwer), 1995.
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1. A. Varma, M.B. Steer, and P.D. Franzon, "Improved IO Buffer Modeling Based on IBIS," to appear in *IEEE Trans. Adv. Pack.*
2. K. Chadrashekar and P.D. Franzon, "Inductively Coupled Connectors and Sockets for Multi-Gbps Pulse Signaling," to appear in *IEEE. Trans. Adv. Pack.*
3. A. Sule, J. Oh, P.D. Franzon, W.R. Davis, "Application Exploration for 3D Integrated Circuits: TCAM, FIFO, and FFT Case Studies", to appear in *IEEE Trans. VLSI*.
4. A.S. Blum, C.M. Soto, C.D. Wilson, C. Amsinck, P. Franzon, B.R. Ratna, "Electronic Properties of Molecular Memory Circuits on a Nanoscale Scaffold," in *IEEE Trans NanoBioscience*, 6(4), Dec. 2007, pp. 270-274.
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